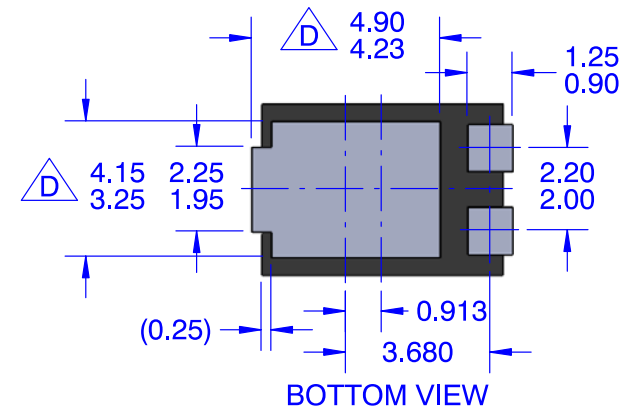
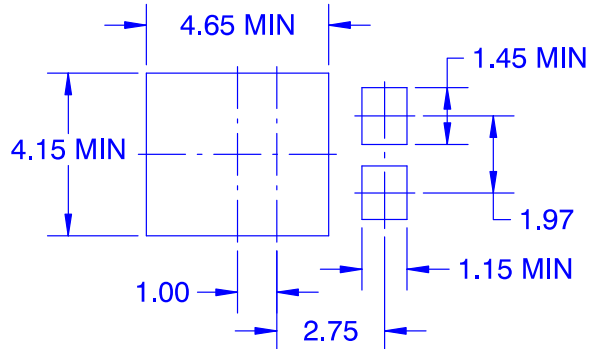
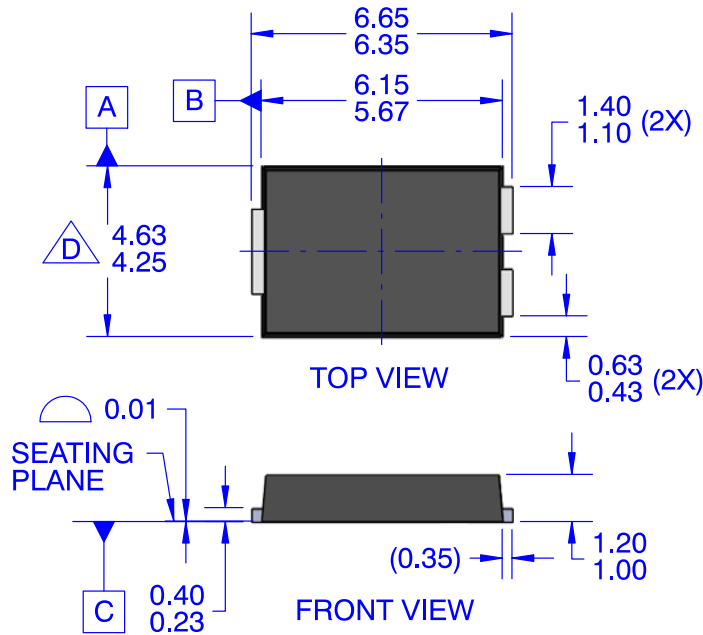


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TO-277-3LD
CASE 340BQ
ISSUE O

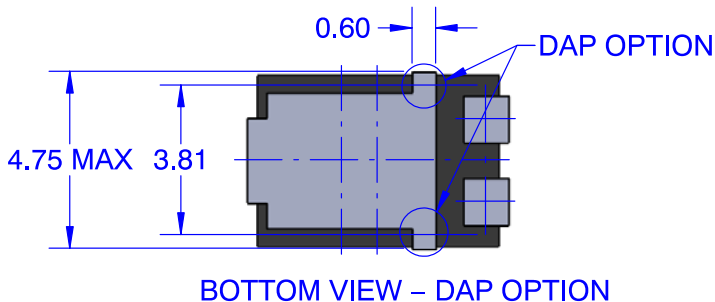
DATE 30 SEP 2016



NOTES: UNLESS OTHERWISE SPECIFIED

- A. PACKAGE REFERENCE: JEDEC TO-277
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.

D DOES NOT COMPLY TO JEDEC STANDARD VALUE.



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DESCRIPTION:	TO-277-3LD	PAGE 1 OF 2

